

Amendment to the Claims:

Please cancel claims 39-63 in this paper.

1-33. (Cancelled)

34. (Previously presented) A tool for electrochemically depositing copper into submicron micro-recesses on a workpiece having a nonuniform copper seed layer less than 500 Å thick, the apparatus comprising:

an automated robotic transfer mechanism;

a plurality of electrochemical processing stations arranged about the robot so that the robot can automatically transfer workpieces to/from the processing stations, the processing stations having baths containing a plating solution including copper and workpiece holders, and the processing stations being configured to operate in a seed layer enhancement mode in which additional copper is electrochemically deposited onto the workpiece to enhance the seed layer for filling the recesses and a bulk plating mode in which copper is electroplated onto the workpiece until the recesses are filled.

35. (Previously presented) The apparatus of claim 34 wherein the electrochemical processing stations include a first processing station configured to operate in the seed layer enhancement mode and a second processing station configured to operate in the bulk plating mode.

36. (Previously presented) The apparatus of claim 34 wherein the first electrochemical processing station comprises a first workpiece holder having first electrical contacts and a first bath comprising an alkaline plating solution, and the second electrochemical processing station comprises a second workpiece holder having second electrical contacts and a second bath comprising an acidic plating solution.

37. (Previously presented) The apparatus of claim 34 wherein the electrochemical processing stations include at least one processing station that can operate in the enhancement mode to enhance the seed layer and then operate in the bulk plating mode to fill the recesses.

38. (Previously presented) The apparatus of claim 34 wherein the electrochemical processing stations include at least one processing station that operates in the enhancement mode by electroplating additional material onto the seed layer.

39-63. (Cancelled)